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FDS6690A

Single N-Channel, Logic-Level, PowerTrench® MOSFET

General Description

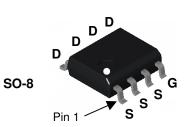
This N-Channel Logic Level MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

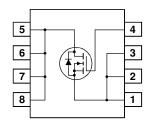
These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.



Features

- 11 A, 30 V. $R_{DS(ON)} \, = 12.5 \; m\Omega \; @ \; V_{GS} = 10 \; V$ $R_{DS(ON)} \, = 17.0 \; m\Omega \; @ \; V_{GS} = 4.5 \; V$
- · Fast switching speed
- · Low gate charge
- High performance trench technology for extremely low Rps/ONL
- · High power and current handling capability





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	11	Α
	- Pulsed		50	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.0	
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	96	mJ
T _J , T _{STG}	Operating and Storage Junction Temperature Range		−55 to +150	°C

Thermal Characteristics

R _{eJA}	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	(Note 1b)	125	
R _{eJC}	Thermal Resistance, Junction-to-Case	(Note 1)	25	

Package Marking and Ordering Information

Device Marking	Device	Reel Size Tape width		Quantity
FDS6690A	FDS6690A	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics		1			1
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_D = 250 \mu\text{A}$	30			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		25		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
		$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			10	μΑ
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Chara	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1	1.9	3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		- 5		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	$\begin{split} V_{GS} &= 10 \ V, & I_D &= 11 \ A \\ V_{GS} &= 4.5 \ V, & I_D &= 10 \ A \\ V_{GS} &= 10 \ V, I_D &= 11 \ A, T_J &= 125 ^{\circ}C \end{split}$		9.8 12.0 13.7	12.5 17.0 22.0	mΩ
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	50			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, \qquad I_{D} = 11 \text{ A}$		48		S
Dynamic	Characteristics					•
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		1205		pF
Coss	Output Capacitance	f = 1.0 MHz		290		pF
C _{rss}	Reverse Transfer Capacitance			115		pF
R _G	Gate Resistance	V _{GS} = 15 mV, f = 1.0 MHz		2.4		Ω
Switchin	g Characteristics (Note 2)					•
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 15 \text{ V}, \qquad I_D = 1 \text{ A},$		9	19	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		5	10	ns
t _{d(off)}	Turn-Off Delay Time			28	44	ns
t _f	Turn-Off Fall Time	7		9	19	ns
Q _g	Total Gate Charge	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 11 \text{ A},$		12	16	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = 5 V$		3.4		nC
Q _{gd}	Gate-Drain Charge			4.0		nC
Drain-Sc	ource Diode Characteristics	and Maximum Ratings		,		
Is	Maximum Continuous Drain-Source	•			2.1	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \qquad I_S = 2.1 \text{ A (Note 2)}$		0.74	1.2	V
t _{rr}	Diode Reverse Recovery Time	1 11 0 0 0 10 100 0 10 1		24		nS
Q _{rr}	Diode Reverse Recovery Charge	$I_F = 11 \text{ A}, d_{iF}/d_t = 100 \text{ A}/\mu\text{s}$		27		nC

Notes:

R_{8JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{8JC} is guaranteed by design while R_{8CA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1in² pad of 2 oz copper



b) 125°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2 Test: Pulse Width < 300μs, Duty Cycle < 2.0%
3. Starting TJ = 25 °C, L = 3mH, I_{AS} = 8A, V_{DD} = 30V, V_{GS} = 10V

Typical Characteristics

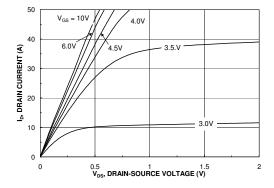


Figure 1. On-Region Characteristics.

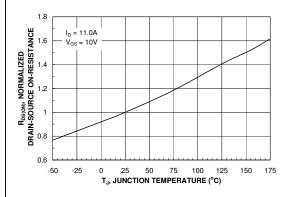


Figure 3. On-Resistance Variation with Temperature.

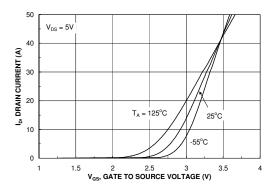


Figure 5. Transfer Characteristics.

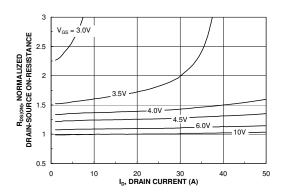


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

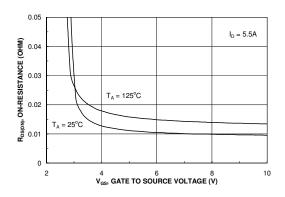


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

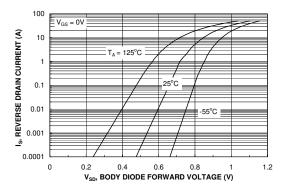
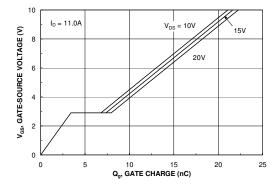


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



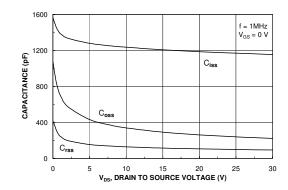
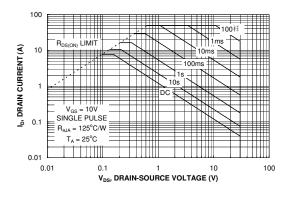


Figure 7. Gate Charge Characteristics.





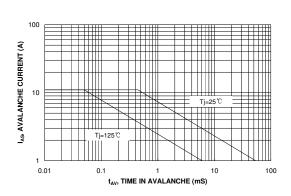
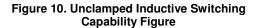


Figure 9. Maximum Safe Operating Area.



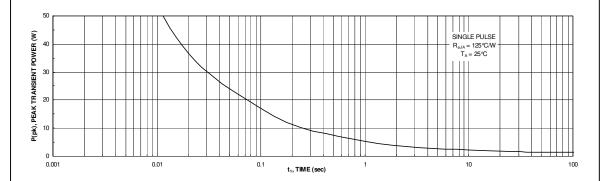


Figure 11. Single Pulse Maximum Power Dissipation.

Typical Characteristic

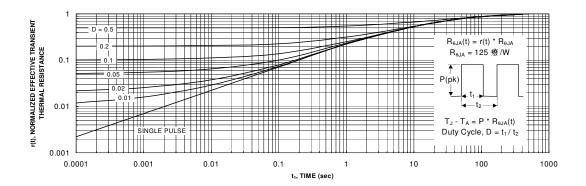


Figure 12. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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